

SOT1155-2

plastic thin fine-pitch ball grid array package; 48 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA48
Package type industry code	TFBGA48
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	- - -
Mounting method type	S (surface mount)
Issue date	19-6-2013

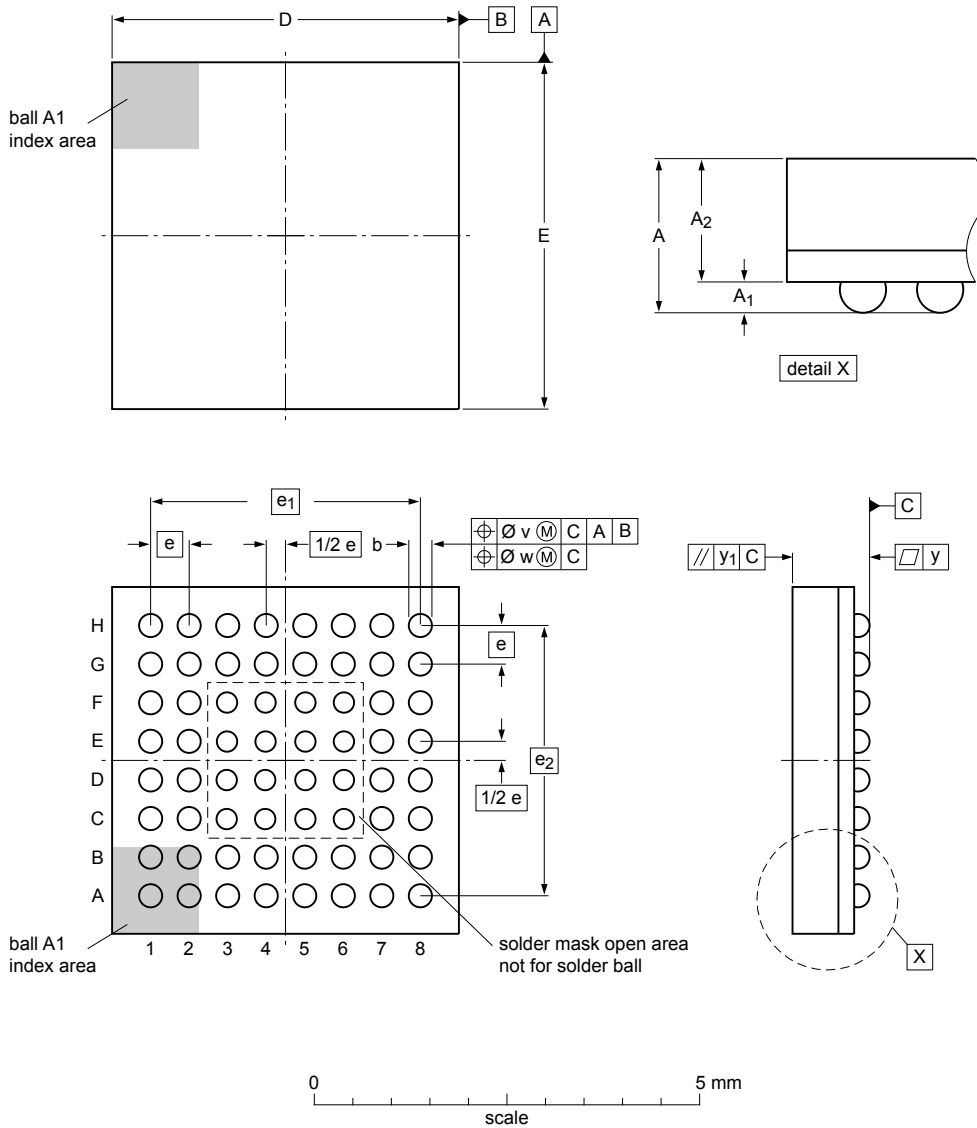
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.4	-	4.5	4.6	mm
E	package width	4.4	-	4.5	4.6	mm
A	seated height	0.85	-	0.95	1.1	mm
A ₂	package height	0.65	-	0.7	0.8	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	48	-	



2. Package outline

TFBGA48: plastic thin fine-pitch ball grid array package; 48 balls; body 4.5 x 4.5 x 0.7 mm SOT1155-2



Dimensions

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
max	1.10	0.30	0.80	0.35	4.6	4.6							
mm nom	0.95	0.25	0.70	0.30	4.5	4.5	0.5	3.5	3.5	0.15	0.05	0.08	0.1
min	0.85	0.20	0.65	0.25	4.4	4.4							

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
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Fig. 1. Package outline TFBGA48 (SOT1155-2)

3. Legal information

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